

News



The Society of Plastics Engineers

ENGINEERING PROPERTIES & STRUCTURE DIVISION

December 2005



SPE EPSDIV TOPCON 2006: Recent Advances In Organic And Polymer Display Technologies

October 23-24, 2006
The University of Akron, Ohio

Call for Papers



Photo courtesy of the University of Akron

This topical conference will provide an update on the latest research in display technologies, with an emphasis on molecular and polymer light emitting materials and liquid crystal polymers. Major technical challenges will be addressed. Focus will be on materials design rules and processing and fabrication technologies. Confirmed invited speakers include:

Dr. Ching Tang (Eastman Kodak Company)
Dr. Mike Lu (Universal Display Corporation)
Prof. Mary Galvin (University of Delaware)
Prof. Tom Jackson (Pennsylvania State University)
Prof. Stephen Cheng (University of Akron)
Prof. Satyen Kumar (Kent State University)

Topics of Interest include but are not limited to liquid crystal and polymers materials design and synthesis; photolithographic and non-conventional patterning and processing technologies for device fabrication; device characterization; lifetimes and reliability.

Abstract Submission Deadline: February 1, 2006

Please submit abstracts to:

Prof. Lynn Loo, Technical Program Chair

Department of Chemical Engineering, University of Texas, Austin, CPE 4.422, C0400,
Austin, TX 78712

Tel: 512-471-6300, Fax: 512-471-7060, Email: lluo@che.utexas.edu

Registration: <http://www.4spe.org/conf/epsdiv06/0610epsdiv.php>

Local Organizing Committee: Shing-Chung Josh Wong (Chair), Sadhan Jana, Cameron Fraser, Kaan Gunes, Lloyd A. Goettler, University of Akron, SPE Akron Section

10 27 2004



May 7-11, 2006
Charlotte Convention Center
Charlotte, North Carolina

Register now to attend ANTEC 2006 – the premier event in the plastics industry – and save money! A reduced registration fee is available until April 14, 2006.

Download registration forms from the SPE website: www.4spe.org.

Charlotte offers the best of southern traditions and hospitality, combined with the excitement, attractions, dining and hotels of a modern, world-class city. Not only will ANTEC attendees be stimulated by the best of the plastics industry, they can also enjoy culture, sports, sightseeing.

Anyone involved with plastics will benefit from attending ANTEC 2006. ANTEC is the single largest technical conference for the plastics industry in the world. Forums provide cutting-edge technological solutions and update issues to plastic professionals. There are forums and sessions for working engineers, R&D scientists, technicians, technical sales people, technical support personnel, academia and managers in the plastics industry.

Attendees gain a greater understanding of the impact of new technology, broaden their understanding of plastic industry, build new skills, network, and recharge their careers.

Engineering Properties and Structures Division will be presenting over 60 papers.

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ANTEC, TOPCON will be exciting events



Hoang Pham,
Chairperson 2005-2006

Dear EPSDIV members,

With the holiday season, I am sure that most members enjoyed a wonderful year-end celebration. I like to take this opportunity to wish every member "Best Wishes for the New Year". It's also a good time to reflect on the accomplishments of EPSDIV and take a peek at the future.

Growth and technology for the future have been our focus for this year. Over the past three months, EPSDIV members had contributed greatly to the efforts of moving the Division towards the future.

EPSDIV members worked very hard to finalize our sponsorship of a Topical Conference (TOPCON) scheduled for October 2006 in Akron, Ohio. This conference is co-sponsored by the Akron SPE Section, and is organized by Professor Josh Wong, University of Akron and the EPSDIV TOPCON Committee chaired by Jeff Gilmore, Eastman Chemical. This is an important step in achieving our objective to reach out to our technical community. More details of the TOPCON can be found on page 1 of this newsletter. I encourage mem-

bers to participate in this conference and enjoy the benefits of scientific exchange, business contacts and insights to industry trends and academic researches.

Our technology drive for the EPSDIV sessions at ANTEC 2006 is very promising. We have a total of 76 abstracts submitted into seven different topical sessions covering Nanotechnology, Surface Treatment, Polymer Properties and Analysis, Films and Fibers and New Trends in Engineering Polymers.

An important aspect of growth for our division is the membership drive. I encourage EPSDIV members to participate in the AIM (Action Increases Membership) program.

I truly believe that we are making progress and the EPSDIV is on track to achieve its plans to face the future. Best wishes to every member.

—Hoang Pham



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**Encourage membership
in EPSDIV**

Are SPE Dues Tax Deductible?

—By Bragrodia Shriram

The legal counsel of a large New York-based engineering society delivered an opinion, derived from interpretation of two rulings from the Internal Revenue Service, that a portion of Society dues are tax-deductible as a charitable contribution if certain conditions are met.

In the case of SPE, the amount of \$74.00 can be deducted as a charitable contribution if you itemize contributions.

This sum is the difference between total dues (\$112.00) and the amount applied as a member subscription to Plastics Engineering (\$38.00), as stated on the dues invoice.

The full sum of \$112.00 can be used to compile the aggregate amount of miscellaneous deductions, of which that in excess of 2% of the taxpayer's adjusted gross income can be deducted.

Remember, however, you can't deduct any portion of your dues twice. It's an "either or" situation.

Revamping the SPE Constitution continues



Don Witenhafer

The SPE Conference Committee approved the application for our Topcon in October 2006.

At the Divisions Committee, the Pinnacle and Pride Awards were changed once again. We can apply for the PRIDE award this year (2005) because the Pinnacle award was changed to run along with the terms of office of boards (ie June to June). The first Pinnacle award will be given at ANTEC 2007. The first step in the Pinnacle award is to turn in our Pinnacle Plan in November followed by our award application the following November where we describe how we performed relative to the plan submitted a year earlier. The award will be judged by a committee of SPE members, not by staff.

The Constitution and Bylaws Committee has been working for over two years to merge the SPE Constitu-

tion and Bylaws into a new document called the Bylaws. The basic problem is that the SPE Constitution has not been amended since 1973 to bring it up to date.

It is a very difficult task to amend the Constitution since it requires a two-thirds vote of the membership and 20% of the membership must vote. Getting 20% of our membership to return a ballot is a daunting task.

It is proposed to amend the Constitution by repealing it and replacing it with the new Bylaws. The new Bylaws can be amended by holding a first reading of the proposed change at a Council meeting followed by notification of all SPE members of the proposed change. A 2/3 vote of the Council at a subsequent meeting will amend the new Bylaws.

Thus changes will be difficult but not nearly as difficult as at present. It may take a lot of help from section and division boards to encourage a 20% voter turnout to repeal the Constitution. It has not yet been determined how the balloting will take place. An electronic ballot is desired but may not be legal under the existing Constitution, which specifies letter ballot.

We are consulting with our SPE legal counsel. This is but one example of how the SPE Constitution is outdated.

A special meeting of the SPE membership will be called in Albuquerque in conjunction with the January Council meeting to formally present this proposal to the membership. If any member wishes to attend, they are welcome.

The SPE budget for next year was approved and it contains a provision to restart section and division rebates. SPE finances are projected to be in the black.

—Don Witenhafer, Councilor

**Good news —
EPSDIV can once
again apply for
PRIDE awards.**

AIM

Action Increases Membership

Peer-to-peer communication is the most effective way to increase membership.

For more information on the AIM initiative see:

www.4spe.org/communities/Id/aim.php

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2005 — a year in review

By Hoang Pham, EPSDIV Chairperson

I like to take this moment to reflect EPSDIV achievements for 2005 from our Board of Director initiatives.

Technology Enrichment Programs

We had a successful ANTEC 2005 and are in preparation of another outstanding ANTEC 2006. These accomplishments result from the hard work from our TPC, namely **Dr. Sadhan** and **Dr. Grady**.

In addition, we have completed our finalization of sponsoring TOPCON 2006 in Akron, Ohio which was led by **Dr. Gilmore** and **Dr. Wong** and a

group of TOPCON experts including our invited TPC for the TOPCON, **Dr. Loo**.

Membership Drive Program

We have achieved a 2% growth in membership since 2004 and using the SPE membership drive program. We strive to maintain this growth into 2006. Many thanks to the leadership from **Dr. Bopp** and **Dr. Patel**.

Membership Services

In this category, we recognized our members by supplying continuity in supporting the O'Toole Award for best student paper at ANTEC, thanks to the

support from **Honeywell Company**.

Furthermore, our Award and Nomination program this year sponsored three key candidates to SPE Fellows and one for HSM. This is quite significant for our Division.

These accomplishments are made possible by our outstanding BOD members such as **Dr. Bragodia**, **Dr. Rajagopalan**, **Dr. Read**, **Dr. Beatty**, **Dr. Krishnawamy** and **Dr. Pyun**.

In addition, our drive for the PRIDE award for 2006-2007 has been completed by **Dr. Read**.

Communications and Operations

We had a chance to update our operations, thanks to the effort from **Dr. Cangalosi**. We also published two newsletters for 2005 and will be publishing the winter edition sometime soon through the lead from **Dr. Trent**.

We also completed our IRS filing for our 2005 financial statement which was led by **Dr. Crawford**, **Dr. Read** and **Dr. Bragodia**.

Also, we had a strong voice at the SPE council through our representative, **Dr. Witenhaferd**.

I believe that we had a successful year of 2005. We all should be happy with this and enjoy the Happy Holiday season.

I like to take this opportunity to thank everyone for their participations and without your devoted help, I don't think that these accomplishment could have been this successful.

On behalf of the BOD, as chairman, I send my wishes to all of you for a Happy Holiday Season. I am hoping to see the continued efforts that we had put in for 2005 reflects stronger in 2006 as we drive to fulfill our goals.

TPC update

ANTEC 2006 submission deadlines are past

We have a total of approximately 60 papers in six tentative subject areas:

- Fibers and Films,
- Morphology and Properties,
- Polymer Surfaces,
- Nanocomposites,
- New Trends in Engineering
- Properties and Structure,
- New Trends in Polymer Analysis of Polymer Properties.

Each subject area will have at least one invited speaker as well.

I would like to publicly thank all of those who submitted papers, as well as all of those who reviewed those papers in a timely fashion.

See you in Charlotte!

—Dr. Brian P. Grady

Engineering Properties and Structure Division FINANCIAL REPORT

Beginning July 1, 2004 to June 30, 2005

BALANCE as of July 1, 2004 **\$28,581.34**

(Cash, checking, savings, investments)

INCOME	ACTUAL	BUDGET	VARIANCE
Interest and Dividends	952.41		(47.59)
Newsletter Ads/Sponsorship	6,000.00	12,000.00	(6,000.00)
Scholarship Contributions		1,000.00	(1,000.00)
ANTEC Sponsorships	4,459.50	5,000.00	(540.50)
TOTAL INCOME	11,411.91	19,000.00	(7,588.09)
TOTAL FUNDS AVAILABLE	\$39,993.25		
EXPENSES	ACTUAL	BUDGET	VARIANCE
General Office Expenses	—	100.00	(100.00)
Board Meetings	2,297.78	3,500.00	(1,202.22)
Newsletter	1,949.10	12,500.00	(10,550.90)
Awards	1,527.69	2,500.00	(972.31)
Scholarships/Grants	—	1,000.00	(1,000.00)
ANTEC Expenses	2,156.80	4,000.00	(1,843.20)
Councilor Travel	1,300.48	1,500.00	(199.52)
Travel		4,000.00	(4,000.00)
Msc. Exp.		200.00	(200.00)
Membership		500.00	(500.00)
TOTAL EXPENSES	9,231.85	29,800.00	(20,563.15)
ENDING BALANCE	\$30,761.40		
Allocation of Funds			
Checking Account		4,149.61	
Savings Account		26,611.79	
TOTAL		\$30,761.40	

Submitted by—
Emmett Crawford, Treasurer

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upcoming events

International Polyolefins Conference 2006, February 26 - March 2, Houston, Texas. From Reserves to Retailers — The Changes Overtaking the Polyolefins Business Worldwide.

Global Environmental Conference (GPEC 2006) February 28 - March 2, Atlanta, Georgia. Conference subjects provide valuable updates on the latest innovations and technologies including reduction in cost, and improvement in quality.

SPE Industrial Thermoforming Symposium & Workshop For Thin & Heavy Gauge Thermoforming. Crowne Plaza Dallas Market Center, Dallas, Texas.

Color Preferences and Consumer Preferences: e-Live™ Presentation January 17, 2006. See the SPE website: www.4spe.org for more information.

Computational Techniques for Characterization and Benchmarking of One-Component Foam (OCF) Cell Structures and Textures — Best of ANTEC — e-Live™ Presentation, January 26, 2006.

Stay update with SPE at www.4spe.org

Reminder... SPE EPSDIV TOPCON 2006

Deadline for abstract
submission is
February 1, 2006

Please submit abstracts to:
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